



Material Content Data Sheet



Sales Product Name				IPB027N10N3 G		Issued		23. January 2018	
MA#				MA001154224					
Package				PG-TO263-3-2		Weight*		1566.43 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	15.446	0.99	0.99	9860	9860	
leadframe	non noble metal	iron	7439-89-6	0.304	0.02		194		
	inorganic material	phosphorus	7723-14-0	0.091	0.01		58		
	non noble metal	copper	7440-50-8	304.026	19.41	19.44	194089	194341	
wire	non noble metal	aluminium	7429-90-5	10.857	0.69	0.69	6931	6931	
encapsulation	organic material	carbon black	1333-86-4	10.025	0.64		6400		
	plastics	epoxy resin	-	110.277	7.04		70400		
	inorganic material	silicondioxide	60676-86-0	548.042	34.99	42.67	349867	426668	
leadfinish	non noble metal	tin	7440-31-5	9.657	0.62	0.62	6165	6165	
plating	non noble metal	nickel	7440-02-0	0.228	0.01		146		
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.01	1	146	
solder	noble metal	silver	7440-22-4	0.227	0.01		145		
	non noble metal	tin	7440-31-5	0.182	0.01		116		
	non noble metal	lead	7439-92-1	8.686	0.55	0.57	5545	5806	
heatspreader	non noble metal	iron	7439-89-6	0.548	0.04		350		
	inorganic material	phosphorus	7723-14-0	0.165	0.01		105		
	non noble metal	copper	7440-50-8	547.666	34.96	35.01	349628	350083	
*deviation	< 10%					Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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